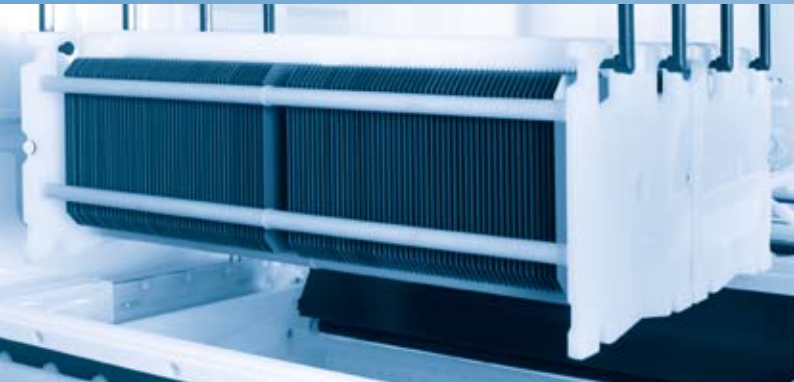


# SOLAR

## BatchTex

RENA



## Fast texturing for high throughput

Texturing tuning by RENA - We minimize the process time to achieve your optimum pyramid size distribution.

You specify the wafer surface, we guarantee reproducible texturing.

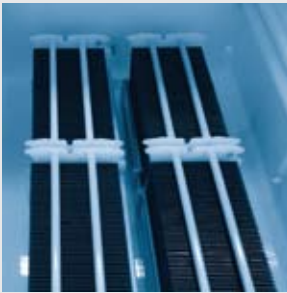
### Areas of application

- Alkaline texturing
  - IPA based
  - IPA + moderating agent based
  - IPA free moderating agent based
- Optimised for RENA monoTEX<sup>®</sup>, IPA free, moderating agent
- Saw damage removal and texturing in one process
- Processing of multi wafer

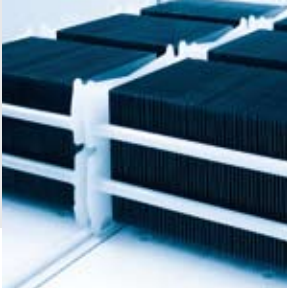
### Features and benefits

- Process guarantee for a wide range of specified wafers
- Suitable for IPA free and IPA based texturing
- Process guarantee for RENA's IPA free monoTEX<sup>®</sup> process
- Total solution
  - Pre -Clean
  - monoTEX<sup>®</sup> process
  - Metal cleaning
- Pre-clean guarantees a monoTEX<sup>®</sup> bath lifetime of >30 runs
- Texturing and metal cleaning area separated by a shutter
- Anti-floating feature in all tanks by special carrier arrangement
- Optionally tank-in-tank design for improved process flexibility and control
- SDE and texturing in one step as standard
- Homogeneous texturing is facilitated by a pre-clean step
- Measurement of the actual silicon removal
- Low consumption of chemicals
- Control of pyramid size to some extent, typically from 3-8  $\mu\text{m}$ , other distributions on request
- Powerful data base for event tracking
- Flexible recipe adaptation
- Filtered intake air for improved metal removal and drying
- Extremely low breakage rate
- High throughput version BatchTex HT, with >4,800 wafers/h also available





Carrier in process tank



Loading buffer



Front view BatchTex

## Technical Data BatchTex

### Process

- Pre-cleaning alkaline, acidic
- Texturing, alkaline, acidic
- Cleaning HCl, HF
- Drying: hot water, warm air, HF/O<sub>3</sub>

### Dimensions

Typical alkaline texturing system for 2800 wafers/h 156 x 156 mm based on monoTEX®  
18580 x 2050 x 2700 mm (length x width x height)

### Throughput

BatchTex 2800 wafers/h  
BatchTex HT > 4800 wafers/h

### Wafer thickness

> 180 µm  
> 120 µm as Customised Batch Solution

### Media consumption

- Compressed air 20 m<sup>3</sup>/h
- Electricity 230/400 V, 50 Hz, 3 Phase, 105 kW peak

### Options

- Process carriers: RENA ASC
- Automatic loading system VarioLoad
- Bulk chemical supply systems
- Process guarantee